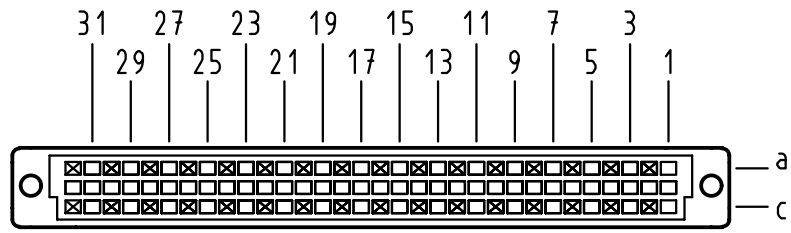


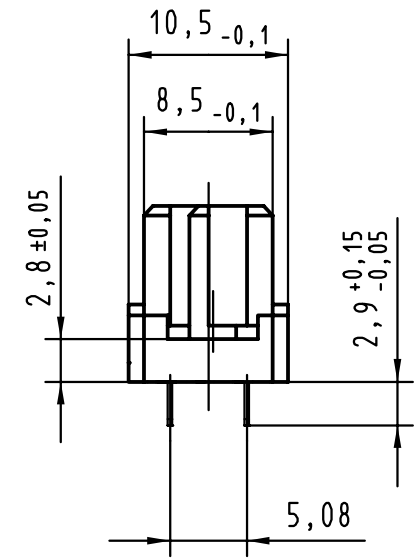
X  
Kontaktanordnung  
Contact arrangement



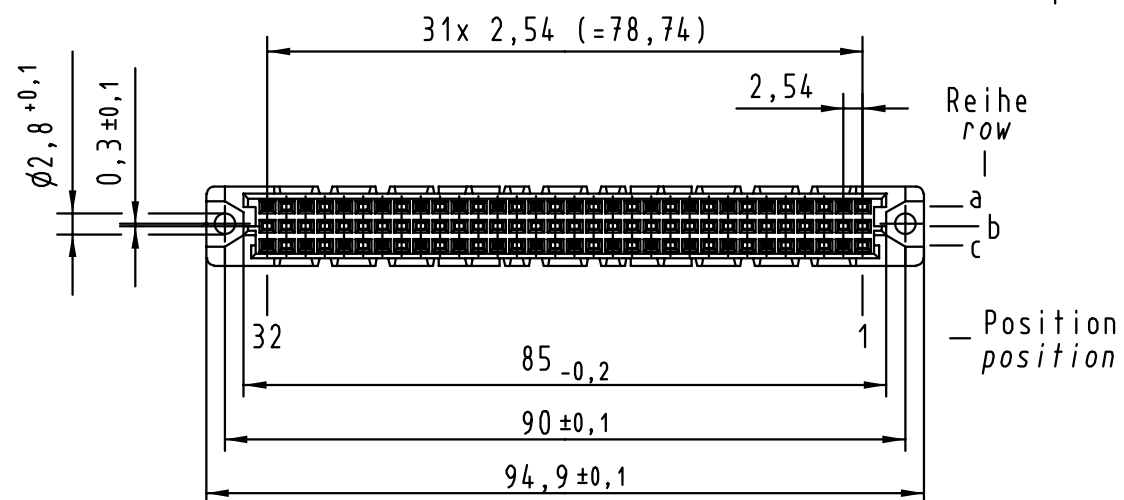
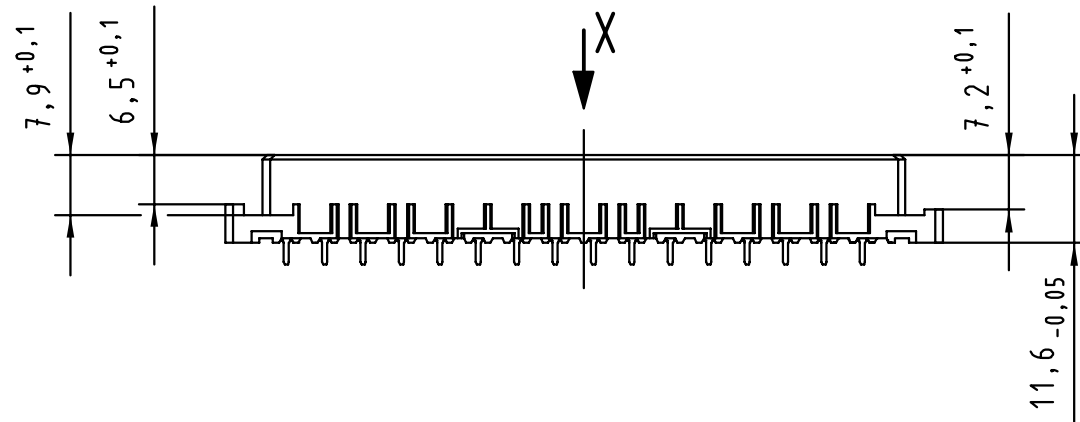
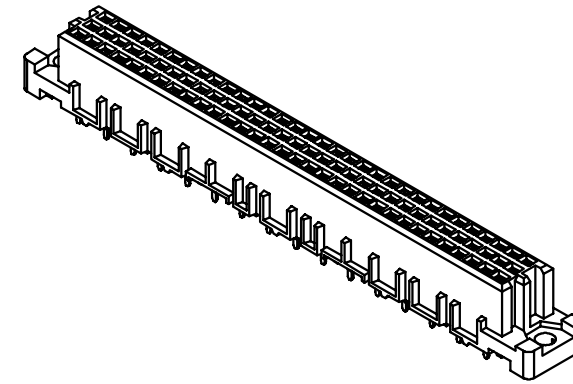
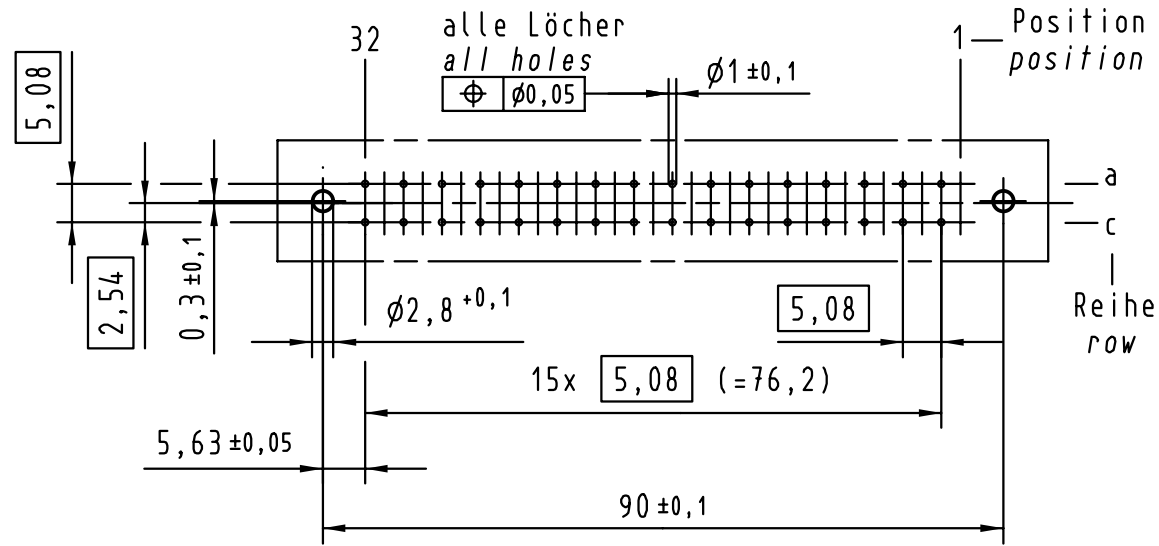
32 Einlöt-Kontakte  
32 solder-contacts

- ⊗ = Einlöt-Kontakt  
= solder-contact
- = kinked Einlöt-Kontakt  
= kinked solder-contact
- = Kontaktposition nicht belegt  
= position without contact

Z  
2:1



X  
(Lochbild)  
(Board drillings)



09 03 232 5824	-	min. 0,76 μm (30 μm) Au über/over min. 1,27 μm (50 μm) Ni
09 03 232 4824	VG	Au über/over Ni
09 03 232 7824	3	Au über/over Ni
09 03 232 6824	2	Au über/over Ni
09 03 232 2824	1	Au über/over Ni
Bestell-Nr. Part-No.	Anforderungsstufe nach IEC performance level per IEC	Kontaktoberfläche Contact Plating

			Techn. Character.			Nicht tolerierte Maße / Free size tolerances siehe / see IEC 603-2		
			Dat.			Name		
			Detail.			Maßstab / Scale		
			Insp.			1:1		
			Stand.			2:1		
26919	12.11.99	Rie.	HARTING KGaA					
26082			D-32339 ESPELKAMP					
Mod.	Dat.	Name				TB 09 03 232 x824		
						Sub.		Blatt / page